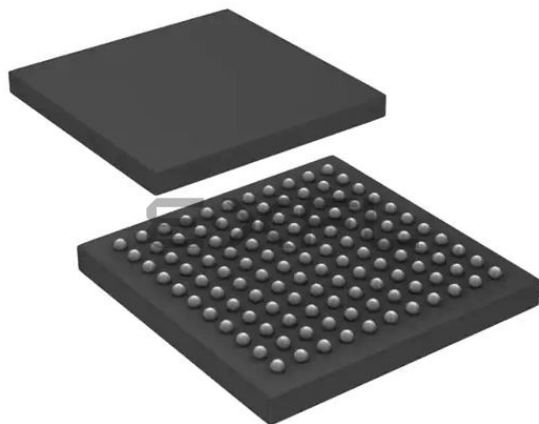




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What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Active
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	80MHz
Connectivity	I ² C, IrDA, LINbus, PMP, SPI, UART/USART, USB OTG
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	-
Program Memory Size	512KB (512K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 16x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	121-TFBGA
Supplier Device Package	121-TFBGA (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx460f512l-80i-bg

PIC32MX3XX/4XX

High-Performance, General Purpose and USB 32-bit Flash Microcontrollers

High-Performance 32-bit RISC CPU:

- MIPS32® M4K® 32-bit core with 5-stage pipeline
- 80 MHz maximum frequency
- 1.56 DMIPS/MHz (Dhrystone 2.1) performance at 0 wait state Flash access
- Single-cycle multiply and high-performance divide unit
- MIPS16e® mode for up to 40% smaller code size
- Two sets of 32 core register files (32-bit) to reduce interrupt latency
- Prefetch Cache module to speed execution from Flash

Microcontroller Features:

- Operating temperature range of -40°C to +105°C
- Operating voltage range of 2.3V to 3.6V
- 32K to 512K Flash memory (plus an additional 12 KB of boot Flash)
- 8K to 32K SRAM memory
- Pin-compatible with most PIC24/dsPIC® DSC devices
- Multiple power management modes
- Multiple interrupt vectors with individually programmable priority
- Fail-Safe Clock Monitor Mode
- Configurable Watchdog Timer with on-chip Low-Power RC Oscillator for reliable operation

Peripheral Features:

- Atomic SET, CLEAR and INVERT operation on select peripheral registers
- Up to 4-channel hardware DMA with automatic data size detection
- USB 2.0-compliant full-speed device and On-The-Go (OTG) controller
- USB has a dedicated DMA channel
- 3 MHz to 25 MHz crystal oscillator
- Internal 8 MHz and 32 kHz oscillators

- Separate PLLs for CPU and USB clocks
- Two I²C™ modules
- Two UART modules with:
 - RS-232, RS-485 and LIN support
 - IrDA® with on-chip hardware encoder and decoder
- Up to two SPI modules
- Parallel Master and Slave Port (PMP/PSP) with 8-bit and 16-bit data and up to 16 address lines
- Hardware Real-Time Clock and Calendar (RTCC)
- Five 16-bit Timers/Counters (two 16-bit pairs combine to create two 32-bit timers)
- Five capture inputs
- Five compare/PWM outputs
- Five external interrupt pins
- High-Speed I/O pins capable of toggling at up to 80 MHz
- High-current sink/source (18 mA/18 mA) on all I/O pins
- Configurable open-drain output on digital I/O pins

Debug Features:

- Two programming and debugging Interfaces:
 - 2-wire interface with unintrusive access and real-time data exchange with application
 - 4-wire MIPS® standard enhanced JTAG interface
- Unintrusive hardware-based instruction trace
- IEEE Standard 1149.2-compatible (JTAG) boundary scan

Analog Features:

- Up to 16-channel 10-bit Analog-to-Digital Converter:
 - 1000 ksps conversion rate
 - Conversion available during Sleep, Idle
- Two Analog Comparators

PIC32MX3XX/4XX

TABLE 4: PIN NAMES: PIC32MX440F128L, PIC32MX460F256L AND PIC32MX460F512L DEVICES

Pin Number	Full Pin Name
A1	PMD4/RE4
A2	PMD3/RE3
A3	TRD0/RG13
A4	PMD0/RE0
A5	PMD8/RG0
A6	PMD10/RF1
A7	ENVREG
A8	Vss
A9	IC5/PMD12/RD12
A10	OC3/RD2
A11	OC2/RD1
B1	No Connect (NC)
B2	RG15
B3	PMD2/RE2
B4	PMD1/RE1
B5	TRD3/RA7
B6	PMD11/RF0
B7	VCAP/VCORE
B8	PMRD/CN14/RD5
B9	OC4/RD3
B10	Vss
B11	SOSCO/T1CK/CN0/RC14
C1	PMD6/RE6
C2	VDD
C3	TRD1/RG12
C4	TRD2/RG14
C5	TRCLK/RA6
C6	No Connect (NC)
C7	PMD15/CN16/RD7
C8	OC5/PMWR/CN13/RD4
C9	VDD
C10	SOSCI/CN1/RC13
C11	IC4/PMCS1/PMA14/RD11
D1	T2CK/RC1
D2	PMD7/RE7
D3	PMD5/RE5
D4	Vss
D5	Vss
D6	No Connect (NC)
D7	PMD14/CN15/RD6
D8	CN19/PMD13/RD13
D9	SDO1/OC1/INT0/RD0
D10	No Connect (NC)
D11	SCK1/IC3/PMCS2/PMA15/RD10
E1	T5CK/SDI1/RC4
E2	T4CK/RC3
E3	SCK2/PMA5/CN8/RG6
E4	T3CK/RC2
E5	VDD
E6	PMD9/RG1
E7	Vss

Pin Number	Full Pin Name
E8	SDA1/INT4/RA15
E9	RTCC/IC1/RD8
E10	SS1/IC2/RD9
E11	SCL1/INT3/RA14
F1	MCLR
F2	SDO2/PMA3/CN10/RG8
F3	SS2/PMA2/CN11/RG9
F4	SDI2/PMA4/CN9/RG7
F5	Vss
F6	No Connect (NC)
F7	No Connect (NC)
F8	Vdd
F9	OSC1/CLKI/RC12
F10	Vss
F11	OSC2/CLKO/RC15
G1	INT1/RE8
G2	INT2/RE9
G3	TMS/RA0
G4	No Connect (NC)
G5	VDD
G6	Vss
G7	Vss
G8	No Connect (NC)
G9	TDO/RA5
G10	SDA2/RA3
G11	TDI/RA4
H1	AN5/C1IN+/VBUSON/CN7/RB5
H2	AN4/C1IN-/CN6/RB4
H3	Vss
H4	VDD
H5	No Connect (NC)
H6	VDD
H7	No Connect (NC)
H8	VBUS
H9	VUSB
H10	D+/RG2
H11	SCL2/RA2
J1	AN3/C2IN+/CN5/RB3
J2	AN2/C2IN-/CN4/RB2
J3	PGED2/AN7/RB7
J4	AVDD
J5	AN11/PMA12/RB11
J6	TCK/RA1
J7	AN12/PMA11/RB12
J8	No Connect (NC)
J9	No Connect (NC)
J10	U1TX/RF8
J11	D-/RG3
K1	PGEC1/AN1/CN3/RB1
K2	PGED1/AN0/CN2/RB0
K3	VREF+/CVREF+/PMA6/RA10

PIC32MX3XX/4XX

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2.5 ICSP Pins

The PGECx and PGEDx pins are used for In-Circuit Serial Programming™ (ICSP™) and debugging purposes. It is recommended to keep the trace length between the ICSP connector and the ICSP pins on the device as short as possible. If the ICSP connector is expected to experience an ESD event, a series resistor is recommended, with the value in the range of a few tens of Ohms, not to exceed 100 Ohms.

Pull-up resistors, series diodes and capacitors on the PGECx and PGEDx pins are not recommended as they will interfere with the programmer/debugger communications to the device. If such discrete components are an application requirement, they should be removed from the circuit during programming and debugging. Alternately, refer to the AC/DC characteristics and timing requirements information in the respective device Flash programming specification for information on capacitive loading limits and pin input voltage high (V_{IH}) and input low (V_{IL}) requirements.

Ensure that the "Communication Channel Select" (i.e., PGECx/PGEDx pins) programmed into the device matches the physical connections for the ICSP to MPLAB® ICD 2, MPLAB ICD 3 or MPLAB REAL ICE™.

For more information on ICD 2, ICD 3 and REAL ICE connection requirements, refer to the following documents that are available on the Microchip web site.

- "MPLAB® ICD 2 In-Circuit Debugger User's Guide" DS51331
- "Using MPLAB® ICD 2" (poster) DS51265
- "MPLAB® ICD 2 Design Advisory" DS51566
- "Using MPLAB® ICD 3" (poster) DS51765
- "MPLAB® ICD 3 Design Advisory" DS51764
- "MPLAB® REAL ICE™ In-Circuit Debugger User's Guide" DS51616
- "Using MPLAB® REAL ICE™" (poster) DS51749

2.6 JTAG

The TMS, TDO, TDI and TCK pins are used for testing and debugging according to the Joint Test Action Group (JTAG) standard. It is recommended to keep the trace length between the JTAG connector and the JTAG pins on the device as short as possible. If the JTAG connector is expected to experience an ESD event, a series resistor is recommended, with the value in the range of a few tens of Ohms, not to exceed 100 Ohms.

Pull-up resistors, series diodes and capacitors on the TMS, TDO, TDI and TCK pins are not recommended as they will interfere with the programmer/debugger communications to the device. If such discrete components are an application requirement, they should be removed from the circuit during programming and debugging. Alternately, refer to the AC/DC characteristics and timing requirements information in the respective device Flash programming specification for information on capacitive loading limits and pin input voltage high (V_{IH}) and input low (V_{IL}) requirements.

2.7 Trace

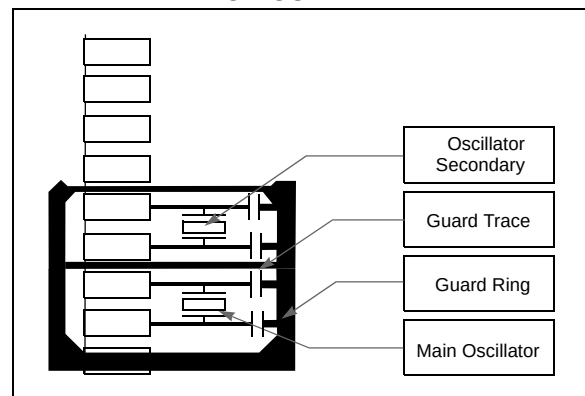
The trace pins can be connected to a hardware-trace-enabled programmer to provide a compress real time instruction trace. When used for trace the TRD3, TRD2, TRD1, TRD0 and TRCLK pins should be dedicated for this use. The trace hardware requires a 22 Ohm series resistor between the trace pins and the trace connector.

2.8 External Oscillator Pins

Many MCUs have options for at least two oscillators: a high-frequency primary oscillator and a low-frequency secondary oscillator (refer to **Section 8.0 "Oscillator Configuration"** for details).

The oscillator circuit should be placed on the same side of the board as the device. Also, place the oscillator circuit close to the respective oscillator pins, not exceeding one-half inch (12 mm) distance between them. The load capacitors should be placed next to the oscillator itself, on the same side of the board. Use a grounded copper pour around the oscillator circuit to isolate them from surrounding circuits. The grounded copper pour should be routed directly to the MCU ground. Do not run any signal traces or power traces inside the ground pour. Also, if using a two-sided board, avoid any traces on the other side of the board where the crystal is placed. A suggested layout is illustrated in Figure 2-3.

FIGURE 2-3: SUGGESTED PLACEMENT OF THE OSCILLATOR CIRCUIT



2.9 Configuration of Analog and Digital Pins During ICSP Operations

If MPLAB ICD 2, ICD 3 or REAL ICE is selected as a debugger, it automatically initializes all of the Analog-to-Digital input pins (ANx) as “digital” pins by setting all bits in the ADPCFG register.

The bits in this register that correspond to the Analog-to-Digital pins that are initialized by MPLAB ICD 2, ICD 3 or REAL ICE, must not be cleared by the user application firmware; otherwise, communication errors will result between the debugger and the device.

If your application needs to use certain Analog-to-Digital pins as analog input pins during the debug session, the user application must clear the corresponding bits in the ADPCFG register during initialization of the ADC module.

When MPLAB ICD 2, ICD 3 or REAL ICE is used as a programmer, the user application firmware must correctly configure the ADPCFG register. Automatic initialization of this register is only done during debugger operation. Failure to correctly configure the register(s) will result in all Analog-to-Digital pins being recognized as analog input pins, resulting in the port value being read as a logic ‘0’, which may affect user application functionality.

2.10 Unused I/Os

Unused I/O pins should not be allowed to float as inputs. They can be configured as outputs and driven to a logic-low state.

Alternately, inputs can be reserved by connecting the pin to Vss through a 1k to 10k resistor and configuring the pin as an input.

3.3 Power Management

The MIPS32® M4K® Processor Core offers a number of power management features, including low-power design, active power management and power-down modes of operation. The core is a static design that supports slowing or halting the clocks, which reduces system power consumption during idle periods.

3.3.1 INSTRUCTION-CONTROLLED POWER MANAGEMENT

The mechanism for invoking power-down mode is through execution of the WAIT instruction. For more information on power management, see **Section 25.0 “Power-Saving Features”**.

3.3.2 LOCAL CLOCK GATING

The majority of the power consumed by the PIC32MX3XX/4XX family core is in the clock tree and clocking registers. The PIC32MX family uses extensive use of local gated-clocks to reduce this dynamic power consumption.

3.4 EJTAG Debug Support

The MIPS32® M4K® Processor Core provides for an Enhanced JTAG (EJTAG) interface for use in the software debug of application and kernel code. In addition to standard user mode and kernel modes of operation, the core provides a Debug mode that is entered after a debug exception (derived from a hardware breakpoint, single-step exception, etc.) is taken and continues until a debug exception return (DERET) instruction is executed. During this time, the processor executes the debug exception handler routine.

The EJTAG interface operates through the Test Access Port (TAP), a serial communication port used for transferring test data in and out of the core. In addition to the standard JTAG instructions, special instructions defined in the EJTAG specification define what registers are selected and how they are used.

PIC32MX3XX/4XX

NOTES:

TABLE 4-6: INTERRUPT REGISTERS MAP FOR THE PIC32MX420F032H DEVICE ONLY⁽¹⁾

Virtual Address (BF88_#)	Register Name	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
1000	INTCON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	SS0	0000
		15:0	—	—	—	MVEC	—	TPC<2:0>			—	—	—	INT4EP	INT3EP	INT2EP	INT1EP	INT0EP	0000
1010	INTSTAT ⁽²⁾	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	SRIPL<2:0>			—	—	VEC<5:0>						0000
1020	IPTMR	31:16	IPTMR<31:0>																0000
		15:0																	0000
1030	IFS0	31:16	I2C1MIF	I2C1SIF	I2C1BIF	U1TXIF	U1RXIF	U1EIF	—	—	—	OC5IF	IC5IF	T5IF	INT4IF	OC4IF	IC4IF	T4IF	0000
		15:0	INT3IF	OC3IF	IC3IF	T3IF	INT2IF	OC2IF	IC2IF	T2IF	INT1IF	OC1IF	IC1IF	T1IF	INT0IF	CS1IF	CS0IF	CTIF	0000
1040	IFS1	31:16	—	—	—	—	—	—	USBIF	FCEIF	—	—	—	—	—	—	—	—	0000
		15:0	RTCCIF	FSCMIF	I2C2MIF	I2C2SIF	I2C2BIF	U2TXIF	U2RXIF	U2EIF	SPI2RXIF	SPI2TXIF	SPI2EIF	CMP2IF	CMP1IF	PMPIF	AD1IF	CNIF	0000
1060	IEC0	31:16	I2C1MIE	I2C1SIE	I2C1BIE	U1TXIE	U1RXIE	U1EIE	—	—	—	OC5IE	IC5IE	T5IE	INT4IE	OC4IE	IC4IE	T4IE	0000
		15:0	INT3IE	OC3IE	IC3IE	T3IE	INT2IE	OC2IE	IC2IE	T2IE	INT1IE	OC1IE	IC1IE	T1IE	INT0IE	CS1IE	CS0IE	CTIE	0000
1070	IEC1	31:16	—	—	—	—	—	—	USBIE	FCEIE	—	—	—	—	—	—	—	—	0000
		15:0	RTCCIE	FSCMIE	I2C2MIE	I2C2SIE	I2C2BIE	U2TXIE	U2RXIE	U2EIE	SPI2RXIE	SPI2TXIE	SPI2EIE	CMP2IE	CMP1IE	PMPIE	AD1IE	CNIE	0000
1090	IPC0	31:16	—	—	—	INT0IP<2:0>			INT0IS<1:0>			—	—	—	CS1IP<2:0>		CS1IS<1:0>		0000
		15:0	—	—	—	CS0IP<2:0>			CS0IS<1:0>			—	—	—	CTIP<2:0>		CTIS<1:0>		0000
10A0	IPC1	31:16	—	—	—	INT1IP<2:0>			INT1IS<1:0>			—	—	—	OC1IP<2:0>		OC1IS<1:0>		0000
		15:0	—	—	—	IC1IP<2:0>			IC1IS<1:0>			—	—	—	T1IP<2:0>		T1IS<1:0>		0000
10B0	IPC2	31:16	—	—	—	INT2IP<2:0>			INT2IS<1:0>			—	—	—	OC2IP<2:0>		OC2IS<1:0>		0000
		15:0	—	—	—	IC2IP<2:0>			IC2IS<1:0>			—	—	—	T2IP<2:0>		T2IS<1:0>		0000
10C0	IPC3	31:16	—	—	—	INT3IP<2:0>			INT3IS<1:0>			—	—	—	OC3IP<2:0>		OC3IS<1:0>		0000
		15:0	—	—	—	IC3IP<2:0>			IC3IS<1:0>			—	—	—	T3IP<2:0>		T3IS<1:0>		0000
10D0	IPC4	31:16	—	—	—	INT4IP<2:0>			INT4IS<1:0>			—	—	—	OC4IP<2:0>		OC4IS<1:0>		0000
		15:0	—	—	—	IC4IP<2:0>			IC4IS<1:0>			—	—	—	T4IP<2:0>		T4IS<1:0>		0000
10E0	IPC5	31:16	—	—	—	—	—	—	—	—	—	—	—	—	OC5IP<2:0>		OC5IS<1:0>		0000
		15:0	—	—	—	IC5IP<2:0>			IC5IS<1:0>			—	—	—	T5IP<2:0>		T5IS<1:0>		0000
10F0	IPC6	31:16	—	—	—	AD1IP<2:0>			AD1IS<1:0>			—	—	—	CNIP<2:0>		CNIS<1:0>		0000
		15:0	—	—	—	I2C1IP<2:0>			I2C1IS<1:0>			—	—	—	U1IP<2:0>		U1IS<1:0>		0000
1100	IPC7	31:16	—	—	—	SPI2IP<2:0>			SPI2IS<1:0>			—	—	—	CMP2IP<2:0>		CMP2IS<1:0>		0000
		15:0	—	—	—	CMP1IP<2:0>			CMP1IS<1:0>			—	—	—	PMP1P<2:0>		PMP1S<1:0>		0000
1110	IPC8	31:16	—	—	—	RTCCIP<2:0>			RTCCIS<1:0>			—	—	—	FSCMIP<2:0>		FSCMIS<1:0>		0000
		15:0	—	—	—	I2C2IP<2:0>			I2C2IS<1:0>			—	—	—	U2IP<2:0>		U2IS<1:0>		0000
1140	IPC11	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	USBIP<2:0>			USBIS<1:0>			—	—	—	FCEIP<2:0>		FCEIS<1:0>		0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: Except where noted, all registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 12.1.1 "CLR, SET and INV Registers"** for more information.

2: This register does not have associated CLR, SET, and INV registers.

TABLE 4-14: DMA GLOBAL REGISTERS MAP FOR PIC32MX340FXXXX/360FXXXX/440FXXXX/460XXXX DEVICES ONLY

Virtual Address (BF88_#)	Register Name	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
3000	DMACON ⁽¹⁾	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	SUSPEND	—	—	—	—	—	—	—	—	—	—	—	—	0000
3010	DMASTAT	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	RDWR	—	DMACH<1:0>	—	0000
3020	DMAADDR	31:16	DMAADDR<31:0>																0000
		15:0																	0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: This register has corresponding CLR, SET and INV registers at its virtual address, plus an offset of 0x4, 0x8 and 0xC, respectively. See **Section 12.1.1 “CLR, SET and INV Registers”** for more information.

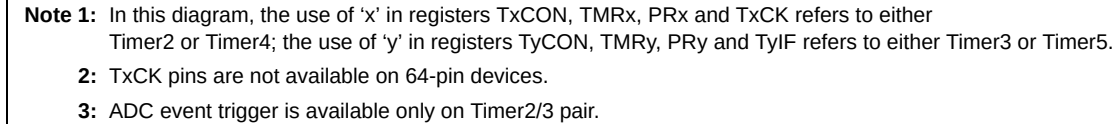
TABLE 4-15: DMA CRC REGISTERS MAP FOR PIC32MX340FXXXX/360FXXXX/440FXXXX/460XXXX DEVICES ONLY⁽¹⁾

Virtual Address (BF88_#)	Register Name	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
3030	DCRCCON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	PLEN<3:0>				CRCEN	CRCAPP	—	—	—	—	CRCCH<1:0>		0000
3040	DCRCDATA	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	DCRCDATA<15:0>																0000
3050	DCRCXOR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	DCRCXOR<15:0>																0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 12.1.1 “CLR, SET and INV Registers”** for more information.

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PIC32MX3XX/4XX

REGISTER 26-6: DDPCON: DEBUG DATA PORT CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	r-X	r-X	r-X	r-X	r-X	r-X	r-X	r-X
	—	—	—	—	—	—	—	—
23:16	r-X	r-X	r-X	r-X	r-X	r-X	r-X	r-X
	—	—	—	—	—	—	—	—
15:8	r-X	r-X	r-X	r-X	r-X	r-X	r-X	r-X
	—	—	—	—	—	—	—	—
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-1	R/W-0	r-X	r-X
	DDPUSB	DDPU1	DDPU2	DDPSPI1	JTAGEN	TROEN	—	—

Legend:

R = Readable bit W = Writable bit P = Programmable bit r = Reserved bit
U = Unimplemented bit -n = Bit Value at POR: ('0', '1', x = Unknown)

bit 31-8 **Reserved:** Write '0'; ignore read

bit 7 **DDPUSB:** Debug Data Port Enable for USB bit
1 = USB peripheral ignores USBFRZ (U1CNFG1<5>) setting
0 = USB peripheral follows USBFRZ setting

bit 6 **DDPU1:** Debug Data Port Enable for UART1 bit
1 = UART1 peripheral ignores FRZ (U1MODE<14>) setting
0 = UART1 peripheral follows FRZ setting

bit 5 **DDPU2:** Debug Data Port Enable for UART2 bit
1 = UART2 peripheral ignores FRZ (U2MODE<14>) setting
0 = UART2 peripheral follows FRZ setting

bit 4 **DDPSPI1:** Debug Data Port Enable for SPI1 bit
1 = SPI1 peripheral ignores FRZ (SPI1CON<14>) setting
0 = SPI1 peripheral follows FRZ setting

bit 3 **JTAGEN:** JTAG Port Enable bit
1 = Enable JTAG Port
0 = Disable JTAG Port

bit 2 **TROEN:** Trace Output Enable bit
1 = Enable Trace Port
0 = Disable Trace Port

bit 1-0 **Reserved:** Write '1'; ignore read

TABLE 29-7: DC CHARACTERISTICS: POWER-DOWN CURRENT (IPD)

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated)		
			Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+105°C for V-Temp		
Parameter No.	Typical ⁽²⁾	Max.	Units	Conditions	
Power-Down Current (IPD) ⁽¹⁾					
DC40	7	30	μA	-40°C	2.3V Base Power-Down Current (Note 6)
DC40a	24	30	μA	+25°C	
DC40b	205	300	μA	+85°C	
DC40h	450	900	μA	+105°C	
DC40c	25	—	μA	+25°C	3.3V Base Power-Down Current
DC40d	9	70	μA	-40°C	3.6V Base Power-Down Current
DC40e	25	70	μA	+25°C	
DC40g	115	200 ⁽⁵⁾	μA	+70°C	
DC40f	200	400	μA	+85°C	
DC40i	470	1200	μA	+105°C	
Module Differential Current					
DC41	—	10	μA	-40°C	2.3V Watchdog Timer Current: ΔI _{WDT} (Notes 3, 6)
DC41a	—	10	μA	+25°C	
DC41b	—	10	μA	+85°C	
DC41g	—	12	μA	+105°C	
DC41c	5	—	μA	+25°C	3.3V Watchdog Timer Current: ΔI _{WDT} (Note 3)
DC41d	—	10	μA	-40°C	3.6V Watchdog Timer Current: ΔI _{WDT} (Note 3)
DC41e	—	10	μA	+25°C	
DC41f	—	12	μA	+85°C	
DC41h	—	15	μA	+105°C	
DC42	—	10	μA	-40°C	2.3V RTCC + Timer1 w/32 kHz Crystal: ΔI _{RTCC} (Notes 3, 6)
DC42a	—	17	μA	+25°C	
DC42b	—	37	μA	+85°C	
DC42h	—	45	μA	+105°C	
DC42c	23	—	μA	+25°C	3.3V RTCC + Timer1 w/32 kHz Crystal: ΔI _{RTCC} (Note 3)
DC42e	—	10	μA	-40°C	3.6V RTCC + Timer1 w/32 kHz Crystal: ΔI _{RTCC} (Note 3)
DC42f	—	30	μA	+25°C	
DC42g	—	44	μA	+85°C	
DC42i	—	44	μA	+105°C	

- Note 1:** Base IPD is measured with all digital peripheral modules disabled. All I/Os are configured as inputs and pulled low. WDT and FSCM are disabled.
- 2:** Data in the “Typical” column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.
- 3:** The Δ current is the additional current consumed when the module is enabled. This current should be added to the base IPD current.
- 4:** Test conditions for ADC module differential current are as follows: Internal ADC RC oscillator enabled.
- 5:** Data is characterized at +70°C and not tested. Parameter is for design guidance only.
- 6:** This parameter is characterized, but not tested in manufacturing.

29.2 AC Characteristics and Timing Parameters

The information contained in this section defines PIC32MX3XX/4XX AC characteristics and timing parameters.

FIGURE 29-1: LOAD CONDITIONS FOR DEVICE TIMING SPECIFICATIONS

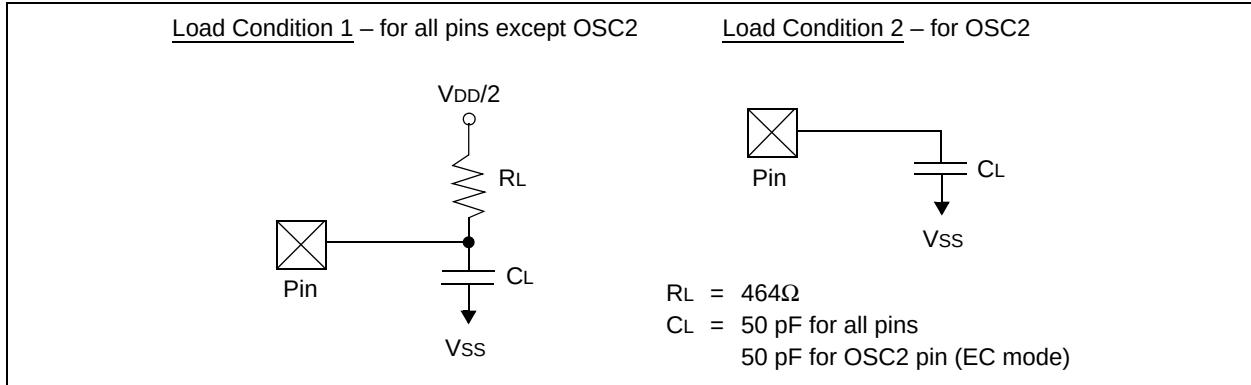


TABLE 29-16: CAPACITIVE LOADING REQUIREMENTS ON OUTPUT PINS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature $-40^\circ\text{C} \leq T_A \leq +85^\circ\text{C}$ for Industrial $-40^\circ\text{C} \leq T_A \leq +105^\circ\text{C}$ for V-Temp				
Param. No.	Symbol	Characteristics	Min.	Typical ⁽¹⁾	Max.	Units	Conditions
DO56	C _{IO}	All I/O pins and OSC2	—	—	50	pF	EC mode
DO58	C _B	SCLx, SDAx	—	—	400	pF	In I ² C™ mode

Note 1: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

FIGURE 29-2: EXTERNAL CLOCK TIMING

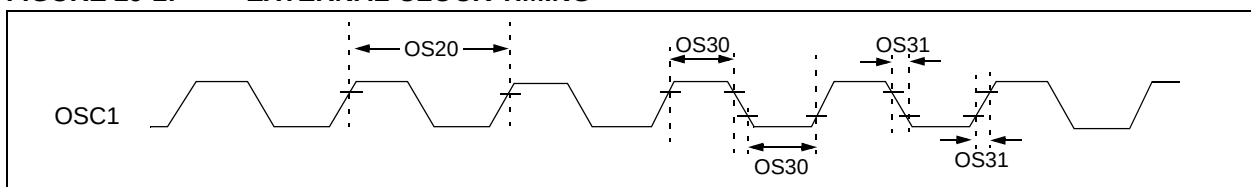


TABLE 29-18: PLL CLOCK TIMING SPECIFICATIONS (V_{DD} = 2.3V TO 3.6V)

AC CHARACTERISTICS		Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤T _A ≤+85°C for Industrial -40°C ≤T _A ≤+105°C for V-Temp					
Param. No.	Symbol	Characteristics ⁽¹⁾	Min.	Typical	Max.	Units	Conditions
OS50	FPLLI	PLL Voltage Controlled Oscillator (VCO) Input Frequency Range	4	—	5	MHz	ECPLL, HSPLL, XTPLL, FRCPLL modes
OS51	FSYS	On-Chip VCO System Frequency	60	—	120	MHz	—
OS52	TLOCK	PLL Start-up Time (Lock Time)	—	—	2	ms	—
OS53	DCLK	CLKO Stability ⁽²⁾ (Period Jitter or Cumulative)	-0.25	—	+0.25	%	Measured over 100 ms period

Note 1: These parameters are characterized, but not tested in manufacturing.

2: This jitter specification is based on clock-cycle by clock-cycle measurements. To get the effective jitter for individual time-bases on communication clocks, use the following formula:

$$EffectiveJitter = \frac{D_{CLK}}{\sqrt{\frac{SYSCLK}{CommunicationClock}}}$$

For example, if SYSCLK = 80 MHz and SPI bit rate = 20 MHz, the effective jitter is as follows:

$$EffectiveJitter = \frac{D_{CLK}}{\sqrt{\frac{80}{20}}} = \frac{D_{CLK}}{2}$$

TABLE 29-19: INTERNAL FRC ACCURACY

AC CHARACTERISTICS		Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤T _A ≤+85°C for Industrial -40°C ≤T _A ≤+105°C for V-Temp				
Param. No.	Characteristics	Min.	Typical	Max.	Units	Conditions
Internal FRC Accuracy @ 8.00 MHz ⁽¹⁾						
F20	FRC	-2	—	+2	%	—

Note 1: Frequency calibrated at 25°C and 3.3V. TUN bits can be used to compensate for temperature drift.

TABLE 29-20: INTERNAL RC ACCURACY

AC CHARACTERISTICS		Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤T _A ≤+85°C for Industrial -40°C ≤T _A ≤+105°C for V-Temp				
Param. No.	Characteristics	Min.	Typical	Max.	Units	Conditions
LPRC @ 31.25 kHz ⁽¹⁾						
F21	LPRC	-15	—	+15	%	—

Note 1: Change of LPRC frequency as V_{DD} changes.

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FIGURE 29-13: SPIx MODULE SLAVE MODE (CKE = 1) TIMING CHARACTERISTICS

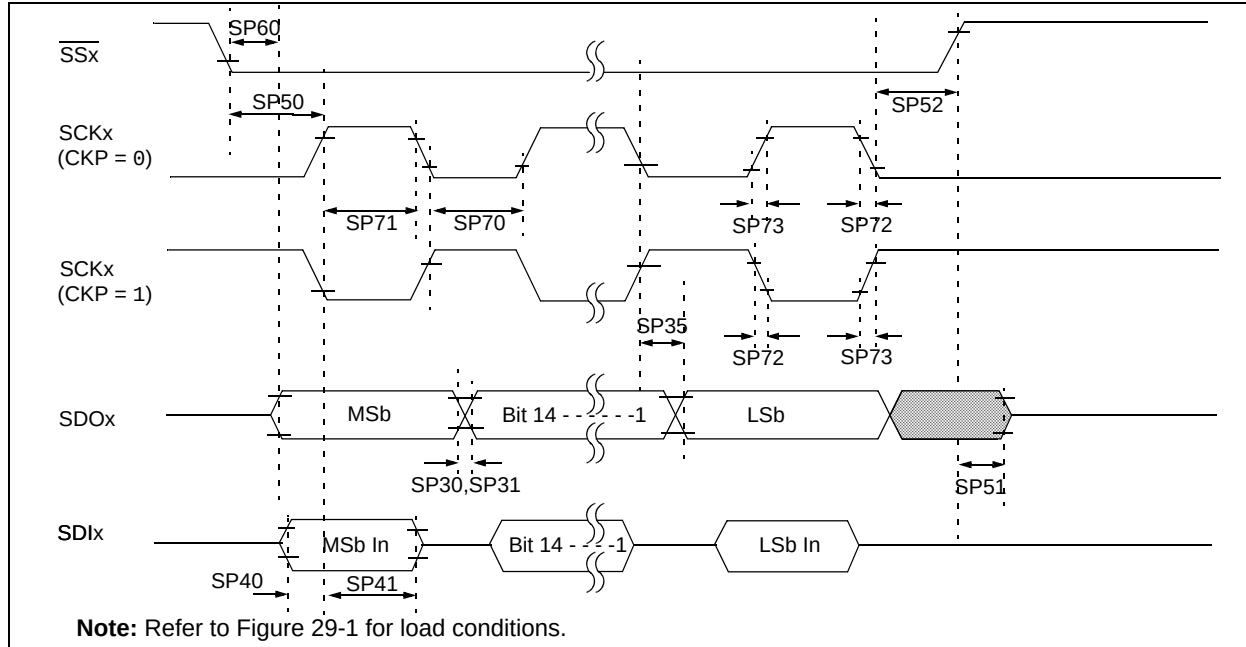


TABLE 29-31: SPIx MODULE SLAVE MODE (CKE = 1) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-Temp				
Param. No.	Symbol	Characteristics ⁽¹⁾	Min.	Typical ⁽²⁾	Max.	Units	Conditions
SP70	TsCL	SCKx Input Low Time ⁽³⁾	TsCK/2	—	—	ns	—
SP71	TsCH	SCKx Input High Time ⁽³⁾	TsCK/2	—	—	ns	—
SP72	TscF	SCKx Input Fall Time	—	5	10	ns	—
SP73	TscR	SCKx Input Rise Time	—	5	10	ns	—
SP30	TdOF	SDOx Data Output Fall Time ⁽⁴⁾	—	—	—	ns	See parameter DO32
SP31	TdOR	SDOx Data Output Rise Time ⁽⁴⁾	—	—	—	ns	See parameter DO31
SP35	TsCH2doV, TsCL2doV	SDOx Data Output Valid after SCKx Edge	—	—	20	ns	VDD > 2.7V
			—	—	30	ns	VDD < 2.7V
SP40	TdIV2sCH, TdIV2sCL	Setup Time of SDIx Data Input to SCKx Edge	10	—	—	ns	—
SP41	TsCH2dIL, TsCL2dIL	Hold Time of SDIx Data Input to SCKx Edge	10	—	—	ns	—
SP50	TssL2sCH, TssL2sCL	SSx ↓ to SCKx ↓ or SCKx ↑ Input	175	—	—	ns	—
SP51	TssH2doZ	SSx ↑ to SDOx Output High-Impedance ⁽⁴⁾	5	—	25	ns	—
SP52	TsCH2ssH, TsCL2ssH	SSx ↑ after SCKx Edge	TsCK + 20	—	—	ns	—
SP60	TssL2doV	SDOx Data Output Valid after SSx Edge	—	—	25	ns	—

Note 1: These parameters are characterized, but not tested in manufacturing.

Note 2: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

Note 3: The minimum clock period for SCKx is 40 ns.

Note 4: Assumes 50 pF load on all SPIx pins.

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TABLE 29-34: ADC MODULE SPECIFICATIONS (CONTINUED)

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-Temp				
Param. No.	Symbol	Characteristics	Min.	Typical	Max.	Units	Conditions
ADC Accuracy – Measurements with Internal VREF+/VREF-							
AD20d	Nr	Resolution	10 data bits			bits	(Note 3)
AD21d	INL	Integral Nonlinearity	—	—	<±1	LSb	VINL = AVSS = 0V, AVDD = 2.5V to 3.6V (Note 3)
AD22d	DNL	Differential Nonlinearity	—	—	<±1	LSb	VINL = AVSS = 0V, AVDD = 2.5V to 3.6V (Notes 2,3)
AD23d	GERR	Gain Error	—	—	<±4	LSb	VINL = AVSS = 0V, AVDD = 2.5V to 3.6V (Note 3)
AD24d	E _{OFF}	Offset Error	—	—	<±2	LSb	VINL = AVSS = 0V, AVDD = 2.5V to 3.6V (Note 3)
AD25d	—	Monotonicity	—	—	—	—	Guaranteed
Dynamic Performance							
AD31b	SINAD	Signal to Noise and Distortion	55	58.5	—	dB	(Notes 3, 4)
AD34b	ENOB	Effective Number of Bits	9.0	9.5	—	bits	(Notes 3, 4)

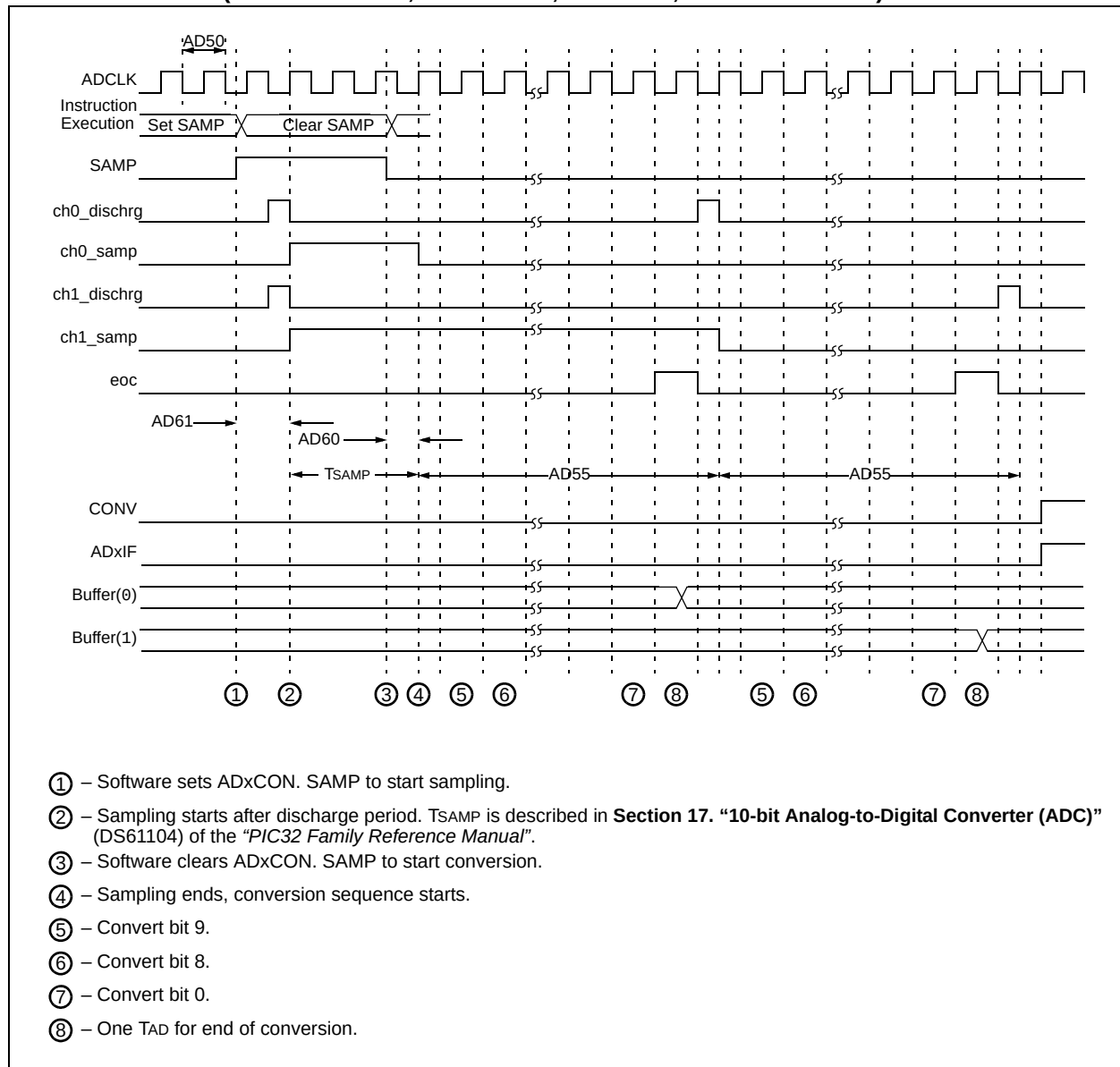
Note 1: These parameters are not characterized or tested in manufacturing.

2: With no missing codes.

3: These parameters are characterized, but not tested in manufacturing.

4: Characterized with 1 kHz sinewave.

FIGURE 29-18: ANALOG-TO-DIGITAL CONVERSION (10-BIT MODE) TIMING CHARACTERISTICS
(CHPS<1:0> = 01, SIMSAM = 0, ASAM = 0, SSRC<2:0> = 000)



PIC32MX3XX/4XX

TABLE A-3: MAJOR SECTION UPDATES (CONTINUED)

Section Name	Update Description
Section 29.0 “Electrical Characteristics”	Added the new V-Temp temperature range (-40°C to +105°C) to the heading of all specification tables. Updated the Ambient temperature under bias, updated the Voltage on any 5V tolerant pin with respect to V_{SS} when V_{DD} < 2.3V, and added Voltage on V_{BUS} with respect to V_{SS} in Absolute Maximum Ratings. Added the characteristic, DC5a to Operating MIPS vs. Voltage (see Table 29-1). Updated or added the following parameters to the Operating Current (I_{DD}) DC Characteristics: DC20, DC23, DC24c, DC25d, DC26c (see Table 29-5). Added the following parameters to the Idle Current (I_{IDLE}) DC Characteristics: DC30c, DC31c, DC32c, DS33c, DC34c, DC35c, and DC36c (see Table 29-6). Added the following parameters to the Power-down Current (I_{PD}) DC Characteristics: DC40g, DC40h, DC40i, DC41g, DC41h, DC42g, DC42h, DC42i, DC43h, and DC43i (see Table 29-7). Added the Brown-out Reset (BOR) Electrical Characteristics (see Table 29-10). Removed all Conditions from the Program Memory DC Characteristics (see Table 29-11). Removed the AC Characteristics voltage reference table (Table 29-15). Added Note 2 to the PLL Clock Timing Specifications (see Table 29-18). Updated the OC/PWM Module Timing Characteristics (see Figure 29-9). Added parameter IM51 and Note 3 to the I2Cx Bus Data Timing Requirements (Master Mode) (see Table 29-32). Added parameter numbers (AD13, AD14, and AD15) to the ADC Module Specifications (see Table 29-34). Updated the 10-bit ADC Conversion Rate Parameters (see Table 29-35). Updated parameter AD57 (TSAMP) in the Analog-to-Digital Conversion Timing Requirements (see Table 29-36). Updated the Conditions for parameters USB313, USB318, and USB319 in the OTG Electrical Specifications (see Table 29-40).
Section 30.0 “Packaging Information”	Updated the 64-Lead Plastic Quad Flat, No Lead Package (MR) – 9x9x0.9 mm Body [QFN] packing diagram.
Product Identification System	Added the new V-Temp (V) temperature information.

Product Identification System

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

	PIC32	MX	3XX	F	512	H	T	- 80	I / PT	- XXX
Microchip Brand										
Architecture										
Product Groups										
Flash Memory Family										
Program Memory Size (KB)										
Pin Count										
Tape and Reel Flag (if applicable)										
Speed										
Temperature Range										
Package										
Pattern										

Examples:

PIC32MX320F032H-40I/PT:
General purpose PIC32MX,
32 KB program memory,
64-pin, Industrial temperature,
TQFP package.

PIC32MX360F256L-80I/PT:
General purpose PIC32MX,
256 KB program memory,
100-pin, Industrial temperature,
TQFP package.

Flash Memory Family	
Architecture	MX = 32-bit RISC MCU core
Product Groups	3XX = General purpose microcontroller family 4XX = USB
Flash Memory Family	F = Flash program memory
Program Memory Size	32 = 32K 64 = 64K 128 = 128K 256 = 256K 512 = 512K
Speed	40 = 40 MHz 80 = 80 MHz
Pin Count	H = 64-pin L = 100-pin
Temperature Range	I = -40° C to +85° C (Industrial) V = -40° C to +105° C (V-Temp)
Package	PT = 64-Lead (10x10x1 mm) TQFP (Thin Quad Flatpack) PT = 100-Lead (12x12x1 mm) TQFP (Thin Quad Flatpack) MR = 64-Lead (9x9x0.9 mm) QFN (Plastic Quad Flat) BG = 121-Lead (10x10x1.1 mm) XBGA (Plastic Thin Profile Ball Grid Array)
Pattern	Three-digit QTP, SQTP, Code or Special Requirements (blank otherwise) ES = Engineering Sample